ATTY DKT. NO.: APPM/7989/ETCH/SILICON/JB

U.S. SERIAL NO.: UNKNOWN CONF. NO.:

FILED: HEREWITH

APPLICANT: APPLIED MATERIALS

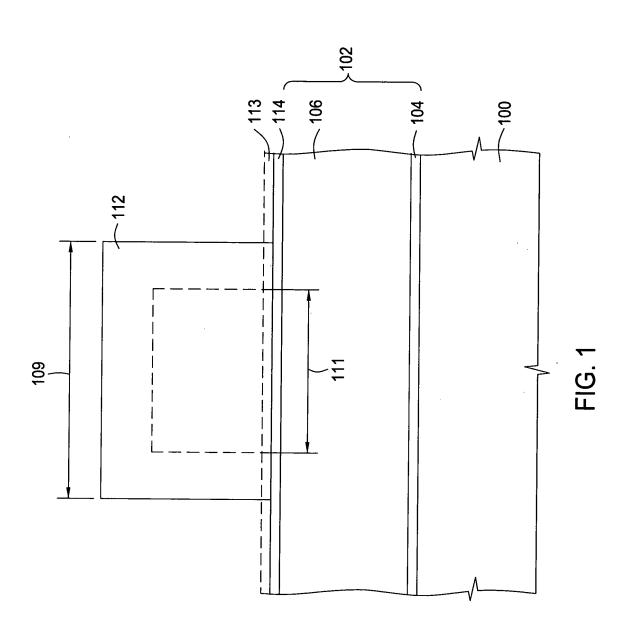
TITLE: METHOD OF CONTROLLING CRITICAL DIMENSION MICROLOADING OF PHOTORESIST TRIMMING PROCESS BY SELECTIVE SIDEWALL POLYMER DEPOSITION

INVENTOR: WEI LIU, ET AL.

EXPRESS MAIL NO.: EL980273124US PAGE 1 OF 4

PAGE 1 OF 4

1/4



ATTY DKT. NO.: APPM/7989/ETCH/SILICON/JB

U.S. SERIAL NO.: UNKNOWN CONF. NO.:
FILED: HEREWITH

APPLICANT: APPLIED MATERIALS

TITLE: METHOD OF CONTROLLING CRITICAL DIMENSION MICROLOADING OF PHOTORESIST TRIMMING PROCESS BY SELECTIVE SIDEWALL POLYMER DEPOSITION

INVENTOR: WEIL JULET ALL

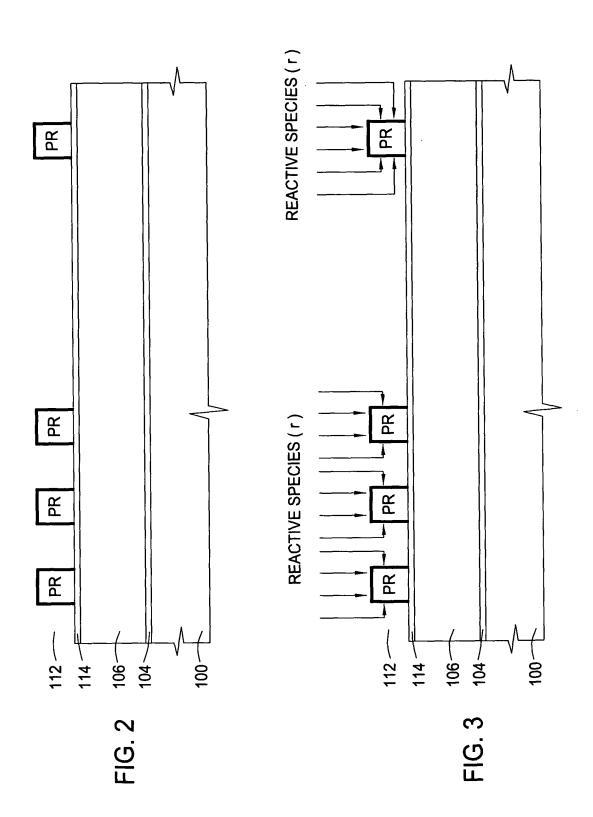
INVENTOR: WEIL JULET ALL

APPM/7989/ETCH/SILICON/JB

CONF. NO.:
FILED:
FIL

INVENTOR: WEI LIU, ET AL. EXPRESS MAIL NO.: EL980273124US PAGE 2 OF 4

2/4



 $\Gamma$ 

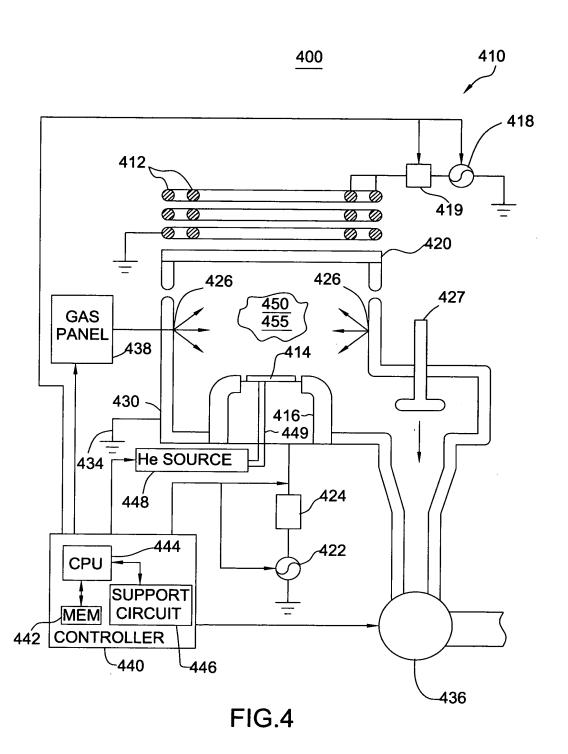
ATTY DKT. NO.: APPM/7989/ETCH/SILICON/JB
U.S. SERIAL NO.: UNKNOWN CONF. NO.:
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: METHOD OF CONTROLLING CRITICAL DIMENSION MICROLOADING OF PHOTORESIST TRIMMING PROCESS BY SELECTIVE SIDEWALL

POLYMER DEPOSITION

INVENTOR: WEI LIU, ET AL. EXPRESS MAIL No.: EL980273124US

PAGE 3 OF 4

3/4



 $\Box$ 

ATTY DKT. NO.: APPM/7989/ETCH/SILICON/JB U.S. SERIAL NO.: UNKNOWN HEREWITH CONF. No.:

FILED:

Γ

APPLICANT: APPLIED MATERIALS

TITLE: METHOD OF CONTROLLING CRITICAL DIMENSION MICROLOADING
OF PHOTORESIST TRIMMING PROCESS BY SELECTIVE SIDEWALL

POLYMER DEPOSITION

INVENTOR: WEI LIU, ET AL.
EXPRESS MAIL NO.: EL980273124US

PAGE 4 OF 4

4/4

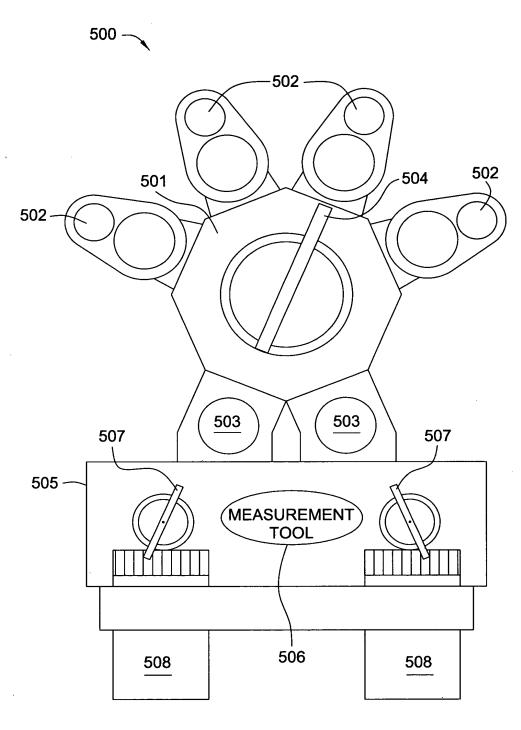


FIG. 5